



## Material Content Data Sheet



<b>Sales Product Name</b>		IPP80N06S4L-07		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001055126						
<b>Package</b>		PG-TO220-3-1		<b>Weight*</b>		2034.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.466	0.12	0.12	1212	1212
leadframe	non noble metal	iron	7439-89-6	0.816	0.04		401	
	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	copper	7440-50-8	815.335	40.10	40.15	400743	401264
wire	non noble metal	aluminium	7429-90-5	5.369	0.26	0.26	2639	2639
encapsulation	organic material	carbon black	1333-86-4	8.940	0.44		4394	
	plastics	epoxy resin	-	98.337	4.83		48333	
	inorganic material	silicondioxide	60676-86-0	488.705	24.02	29.29	240202	292929
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10549	10549
plating	non noble metal	nickel	7440-02-0	0.244	0.01		120	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	400742	120
solder	noble metal	silver	7440-22-4	0.060	0.00		30	
	non noble metal	tin	7440-31-5	0.048	0.00		24	
	non noble metal	lead	7439-92-1	2.297	0.11	0.11	1129	1183
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		290	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	copper	7440-50-8	589.466	28.97	29.01	289727	290104
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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